DATA SHEET



Solid State Relay OCMOS FET

PS7221A-2A

8-PIN SOP, 260 V BREAK DOWN VOLTAGE 2-ch Optical Coupled MOS FET

DESCRIPTION

The PS7221A-2A is a solid state relay containing GaAs LEDs on the light emitting side (input side) and MOS FETs on the output side.

It is suitable for analog signal control because of its low offset and high linearity.

FEATURES

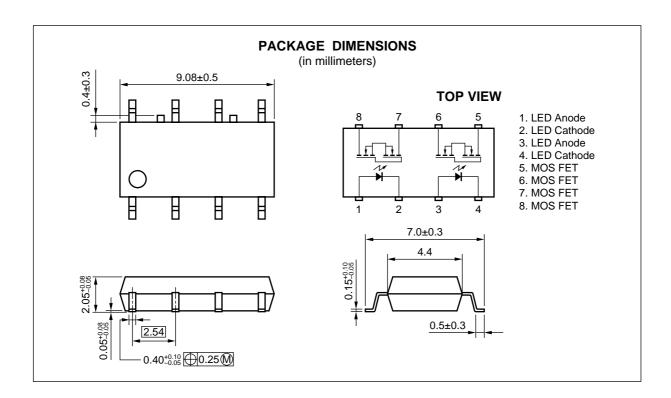
- 2 channel type (1 a + 1 a output)
- Low LED operating current (IF = 1 mA)
- · Designed for AC/DC switching line changer
- Small and thin package (8-pin SOP, Height = 2.1 mm)
- · Low offset voltage
- Ordering number of taping product: PS7221A-2A-F3, F4

APPLICATIONS

- Exchange equipment (FAX, MODEM, OCU + SLIC, etc.)
- Measurement equipment
- FA/OA equipment

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Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.



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ORDERING INFORMATION

Part Number	Package	Packing Style	Application Part Number*1
PS7221A-2A	8-pin SOP	Magazine case 45 pcs	PS7221A-2A
PS7221A-2A -F3		Embossed Tape 1 500 pcs/reel	
PS7221A-2A -F4			

^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	lF	50	mA
	Reverse Voltage	VR	5.0	V
	Power Dissipation	PD	50	mW/ch
	Peak Forward Current [™]	IFP	1	Α
MOS FET	Break Down Voltage	VL	260	V
	Continuous Load Current	IL	170	mA
	Pulse Load Current ^{*2} (AC/DC Connection)	Ігь	300	mA
	Power Dissipation	Po	180	mW/ch
Isolation Voltage*3		BV	1 500	Vr.m.s.
Total Power Dissipation		Рт	460	mW
Operating Ambient Temperature		TA	-40 to +85	°C
Storage Temperature		T _{stg}	-40 to +100	°C

^{*1} PW = 100 μ s, Duty Cycle = 1 %

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^{*2} PW = 100 ms, 1 shot

^{*3} AC voltage for 1 minute at $T_A = 25$ °C, RH = 60 % between input and output



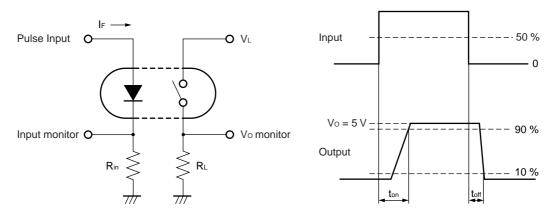
RECOMMENDED OPERATING CONDITIONS (TA = 25 °C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lF	1	10	20	mA
LED Off Voltage	VF	0		0.5	V

ELECTRICAL CHARACTERISTICS (TA = 25 °C)

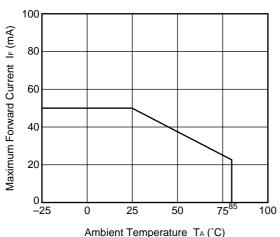
	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	I _F = 5 mA		1.1	1.4	V
	Reverse Current	lR	V _R = 5 V			5.0	μΑ
MOS FET	Off-state Leakage Current	Loff	Vp = 260 V			1.0	μΑ
	Output Capacitance	Cout	V _D = 0 V, f = 1 MHz		122		pF/ch
Coupled	LED On-state Current	IFon	IL = 170 mA			1.0	mA
	On-state Resistance	Ron	IF = 10 mA, IL = 10 mA		3.4	10	Ω
	Turn-on Time ^{*1}	ton	If = 10 mA, Vo = 5 V, RL = 500 Ω ,		0.4	1.0	ms
	Turn-off Time ^{*1}	toff	PW ≥ 10 ms		0.03	0.2	
	Isolation Resistance	R _{I-O}	Vi-o = 1.0 kVpc	10°			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		0.4		pF/ch

*1 Test Circuit for Switching Time

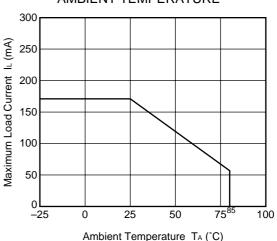


★ TYPICAL CHARACTERISTICS (TA = 25 °C, unless otherwise specified)

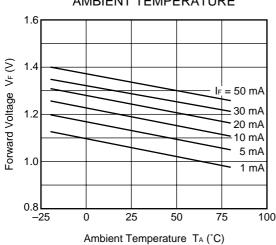




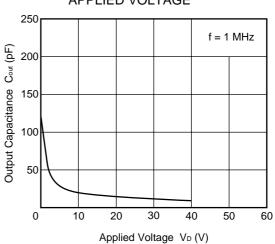
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



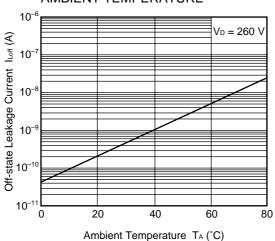
FORWARD VOLTAGE vs. AMBIENT TEMPERATURE



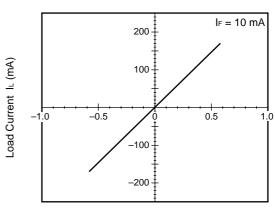
OUTPUT CAPACITANCE vs. APPLIED VOLTAGE



OFF-STATE LEAKAGE CURRENT vs. AMBIENT TEMPERATURE



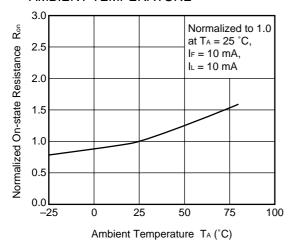
LOAD CURRENT vs. LOAD VOLTAGE



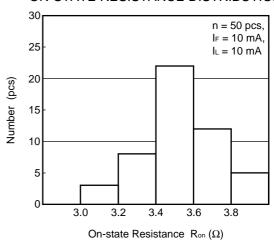
Load Voltage V_L (V)

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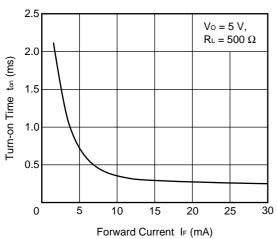
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



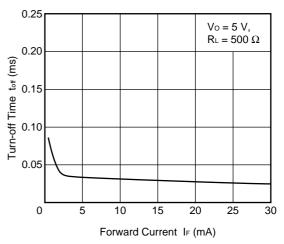
ON-STATE RESISTANCE DISTRIBUTION



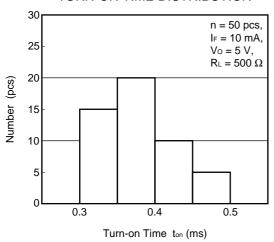
TURN-ON TIME vs. FORWARD CURRENT



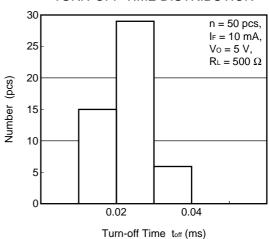
TURN-OFF TIME vs. FORWARD CURRENT



TURN-ON TIME DISTRIBUTION

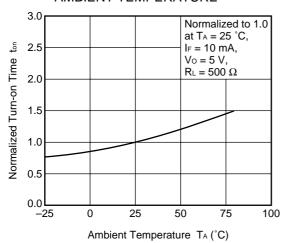


TURN-OFF TIME DISTRIBUTION



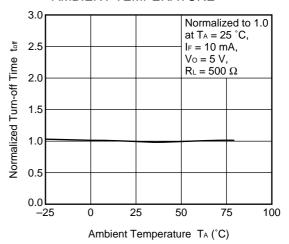
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NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE

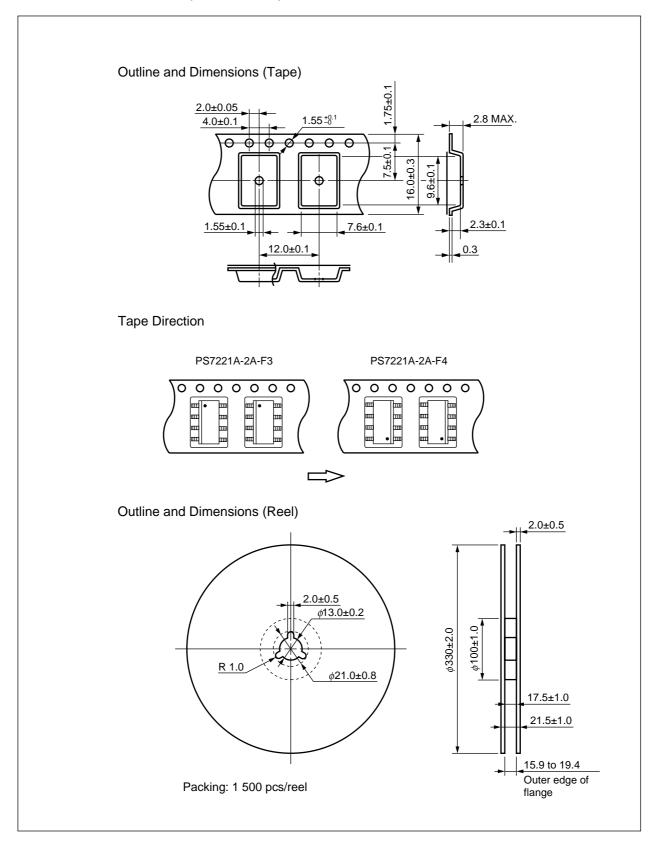


Remark The graphs indicate nominal characteristics.

NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



★ TAPING SPECIFICATIONS (in millimeters)





* RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

• Peak reflow temperature 260°C or below (package surface temperature)

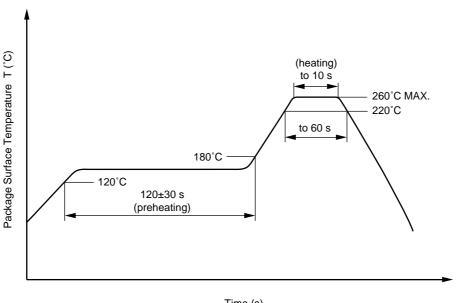
Time of peak reflow temperature
 Time of temperature higher than 220°C
 60 seconds or less

Time to preheat temperature from 120 to 180°C 120±30 s
 Number of reflows Three

Flux
 Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

• Preheating conditions 120°C or below (package surface temperature)

Number of times

• Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

(3) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

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M8E 00.4-0110



SAFETY INFORMATION ON THIS PRODUCT

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GaAs Products

The product contains gallium arsenide, GaAs.

GaAs vapor and powder are hazardous to human health if inhaled or ingested.

- Do not destroy or burn the product.
- Do not cut or cleave off any part of the product.
- Do not crush or chemically dissolve the product.
- Do not put the product in the mouth.

Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.

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